

65,536-Word x 16-Bit Dynamic Random Access Memory

■ DESCRIPTION

The Hitachi HM511664 are CMOS dynamic RAM organized as 65,536-word x 16-bit. HM511664 have realized higher density, higher performance and various functions by employing 0.8 μ m CMOS process technology and some new CMOS circuit design technologies. The HM511664 offer Fast Page Mode as a high speed access mode.

Multiplexed address input permits the HM511664 to be packaged in standard 400 mil 40-pin plastic SOJ, standard 475 mil 40-pin plastic ZIP.

■ FEATURES

- Single 5V ($\pm 10\%$)
- High Speed
 - Access Time80 ns/100 ns (max)
- Low Power Dissipation
 - Active ModeTBD
 - Standby Mode11 mW (max)
- Fast Page Mode Capability
- Byte Write Capability
- 256 Refresh Cycles(4 ms)
- 3 Variations of Refresh
 - RAS Only Refresh
 - CAS Before RAS Refresh
 - Hidden Refresh

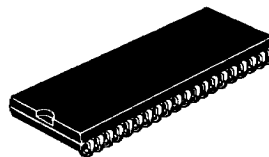
■ ORDERING INFORMATION

Part No.	Access Time	Package
HM511664JP-8 HM511664JP-10	80 ns 100 ns	400 mil 40-pin Plastic SOJ (CP-40D)
HM511664ZP-8 HM511664ZP-10	80 ns 100 ns	475 mil 40-pin Plastic ZIP (ZP-40)

■ PIN DESCRIPTION

Pin Name	Function
A ₀ -A ₇	Address Input Refresh Address Input
I/O ₁ -I/O ₁₆	Data-in/Data-out
RAS	Row Address Strobe
CAS	Column Address Strobe
UW	Read/Upper Byte Write Enable
LW	Read/Lower Byte Write Enable
OE	Output Enable
V _{CC}	Power (+ 5V)
V _{SS}	Ground
NC	No Connection

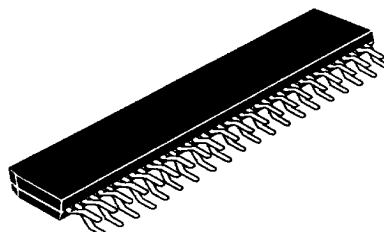
HM511664JP Series



3DCP40D

(CP-40D)

HM511664ZP Series



3DZP40

(ZP-40)

■ PIN OUT

HM511664JP Series

V _{CC} 1	40 V _{SS}
I/O ₁ 2	39 I/O ₁₆
I/O ₂ 3	38 I/O ₁₅
I/O ₃ 4	37 I/O ₁₄
I/O ₄ 5	36 I/O ₁₃
I/O ₅ 6	35 I/O ₁₂
I/O ₆ 7	34 I/O ₁₁
I/O ₇ 8	33 I/O ₁₀
I/O ₈ 9	32 I/O ₉
NC 10	31 NC
V _{CC} 11	30 V _{SS}
UW 12	29 CAS
LW 13	28 OE
RAS 14	27 NC
A ₀ 15	26 NC
A ₁ 16	25 NC
A ₂ 17	24 A ₇
A ₃ 18	23 A ₆
A ₄ 19	22 A ₅
V _{CC} 20	21 V _{SS}

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(Top View)

HM511664ZP Series

I/O ₉ 2	1 NC
I/O ₁₁ 4	3 I/O ₁₀
I/O ₁₃ 6	5 I/O ₁₂
I/O ₁₅ 8	7 I/O ₁₄
V _{SS} 10	9 I/O ₁₆
I/O ₂ 12	11 I/O ₁
I/O ₃ 14	13 V _{CC}
I/O ₅ 16	15 I/O ₄
I/O ₇ 18	17 I/O ₆
NC 20	19 I/O ₈
UW 22	21 V _{CC}
RAS 24	23 LW
A ₁ 26	25 A ₀
A ₃ 28	27 A ₂
V _{CC} 30	29 A ₄
NC 32	31 NC
A ₅ 34	33 V _{SS}
A ₇ 36	35 A ₆
OE 38	37 NC
V _{SS} 40	39 CAS

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(Bottom View)



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■ TRUTH TABLE

Inputs					I/O		Operation
RAS	CAS	$\overline{LW}$	$\overline{UW}$	$\overline{OE}$	I/O ₁ –I/O ₈	I/O ₉ –I/O ₁₆	
H	H	H	H	H	High-Z	High-Z	Standby
L	H	H	H	H	High-Z	High-Z	Refresh
L	L	H	H	L	D _{out}	D _{out}	Read
L	L	L	H	H	D _{in}	Don't Care	Lower Byte Write
L	L	H	L	H	Don't Care	D _{in}	Upper Byte Write
L	L	L	L	H	D _{in}	D _{in}	Word Write
L	L	L	L	H	High-Z	High-Z	

■ ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Voltage on Any Pin Relative to V _{SS}	V _T	– 1.0 to + 7.0	V
Supply Voltage Relative to V _{SS}	V _{CC}	– 1.0 to + 7.0	V
Short Circuit Output Current	I _{out}	50	mA
Power Dissipation	P _T	0.8	W
Operating Temperature	T _{opr}	0 to + 70	°C
Storage Temperature	T _{stg}	– 55 to + 125	°C

■ ELECTRICAL CHARACTERISTICS

• Recommended DC Operating Conditions (T_A = 0 to + 70°C)

Parameter	Symbol	Min	Typ	Max	Unit	Note
Supply Voltage	V _{SS}	0	0	0	V	
	V _{CC}	4.5	5.0	5.5	V	1
Input High Voltage	V _{IH}	2.4	—	6.5	V	1
Input Low Voltage	(I/O _i Pin) V _{IL}	– 0.5	—	0.8	V	1, 2
	(Others) V _{IL}	– 1.0	—	0.8	V	1, 2

Notes: 1. All voltage referenced to V_{SS}.

2. The device will withstand undershoots to the – 2V level with a maximum pulse width of 20 ns at the – 1.5V level. (See figure 1.)

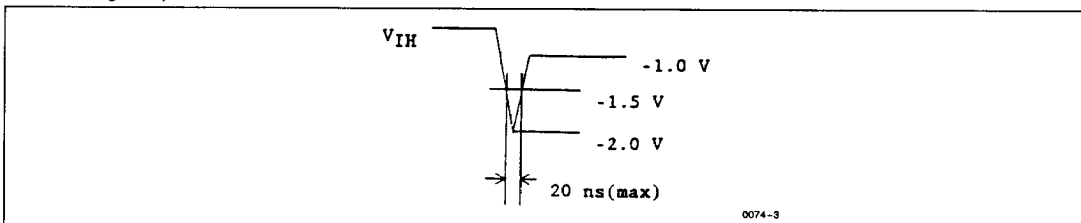


Figure 1. Undershoot of input voltage



• **DC Electrical Characteristics** ($T_A = 0 \text{ to } +70^\circ\text{C}$, $V_{CC} = 5V \pm 10\%$, $V_{SS} = 0V$)

Parameter	Symbol	HM511664-8		HM511664-10		Unit	Test Conditions	Note
		Min	Max	Min	Max			
Operating Current	I_{CC1}	TBD				mA	RAS, CAS Cycling $t_{RC} = \text{Min}$	1, 2
Standby Current	I_{CC2}	2				mA	TTL Interface RAS, CAS = V_{IH} , $D_{out} = \text{High-Z}$	
		1				mA	CMOS Interface RAS, CAS $\geq V_{CC} - 0.2V$, $D_{out} = \text{High-Z}$	
RAS Only Refresh Current	I_{CC3}	TBD				mA	$t_{RC} = \text{Min}$	2
Standby Current	I_{CC5}	TBD				mA	RAS = V_{IH} , CAS = V_{IL} , $D_{out} = \text{Enable}$	1
CAS Before RAS Refresh Current	I_{CC6}	TBD				mA	$t_{RC} = \text{Min}$	
Fast Page Mode Current	I_{CC7}	TBD				mA	$t_{PC} = \text{Min}$	1, 3
Input Leakage Current	I_{LI}	-10	10	-10	10	μA	$0V \leq V_{in} \leq 6.5V$	
Output Leakage Current	I_{LO}	-10	10	-10	10	μA	$0V \leq V_{out} \leq 5.5V$, $D_{out} = \text{Disable}$	
Output High Voltage	V_{OH}	2.4	V_{CC}	2.4	V_{CC}	V	High $I_{out} = -2.5 \text{ mA}$	
Output Low Voltage	V_{OL}	0	0.4	0	0.4	V	Low $I_{out} = 2.1 \text{ mA}$	

- Notes: 1. I_{CC} depends on output load condition when the device is selected, I_{CC} max is specified at the output open condition.
 2. Address can be changed once or less while $\overline{\text{RAS}} = V_{IL}$.
 3. Address can be changed once or less while $\overline{\text{CAS}} = V_{IH}$.

• **Capacitance** ($T_A = 25^\circ\text{C}$, $V_{CC} = 5V \pm 10\%$)

Parameter	Symbol	Typ	Max	Unit	Note
Input Capacitance (Address)	C_{I1}	—	5	pF	1
Input Capacitance (Clocks)	C_{I2}	—	7	pF	1
Output Capacitance (Data-in, Data-out)	$C_{I/O}$	—	7	pF	1, 2

- Notes: 1. Capacitance measured with Boonton Meter or effective capacitance measuring method.
 2. $\overline{\text{CAS}} = V_{IH}$ to disable D_{out} .



HM511664 Series

• AC Characteristics ($T_A = 0$ to $+70^\circ\text{C}$, $V_{CC} = 5V \pm 10\%$, $V_{SS} = 0V$)^{1, 14, 15, 16}

Read, Write, Read-Modify-Write and Refresh Cycles (Common Parameters)

Parameter	Symbol	HM511664-8		HM511664-10		Unit	Note
		Min	Max	Min	Max		
Random Read or Write Cycle Time	t_{RC}	135	—	170	—	ns	
RAS Precharge Time	t_{RP}	45	—	60	—	ns	
RAS Pulse Width	t_{RAS}	80	10000	100	10000	ns	
CAS Pulse Width	t_{CAS}	30	10000	40	10000	ns	
Row Address Setup Time	t_{ASR}	0	—	0	—	ns	
Row Address Hold Time	t_{RAH}	10	—	10	—	ns	
Column Address Setup Time	t_{ASC}	0	—	0	—	ns	
Column Address Hold Time	t_{CAH}	15	—	15	—	ns	
RAS to CAS Delay Time	t_{RCD}	20	50	20	60	ns	8
RAS to Column Address Delay Time	t_{RAD}	15	35	15	45	ns	9
RAS Hold Time	t_{RSH}	30	—	40	—	ns	
CAS Hold Time	t_{CSH}	80	—	100	—	ns	
CAS to RAS Precharge Time	t_{CRP}	10	—	10	—	ns	
OE to D_{in} Delay Time	t_{ODD}	15	—	15	—	ns	
OE Delay Time from D_{in}	t_{DZO}	0	—	0	—	ns	
CAS Setup Time from D_{in}	t_{DZC}	0	—	0	—	ns	
Transition Time (Rise and Fall)	t_T	3	50	3	50	ns	7
Refresh Period	t_{REF}	—	4	—	4	ms	

Read Cycle

Parameter	Symbol	HM511664-8		HM511664-10		Unit	Note
		Min	Max	Min	Max		
Access Time from $\overline{RAS}$	t_{RAC}	—	80	—	100	ns	2, 3
Access Time from $\overline{CAS}$	t_{CAC}	—	30	—	40	ns	3, 4, 13
Access Time from Address	t_{AA}	—	45	—	55	ns	3, 5, 13
Access Time from $\overline{OE}$	t_{OAC}	—	30	—	40	ns	
Read Command Setup Time	t_{RCS}	0	—	0	—	ns	
Read Command Hold Time to $\overline{CAS}$	t_{RCH}	0	—	0	—	ns	
Read Command Hold Time to $\overline{RAS}$	t_{RRH}	0	—	0	—	ns	
Column Address to RAS Lead Time	t_{RAL}	45	—	55	—	ns	
Output Buffer Turn-off Time	t_{OFF1}	0	20	0	20	ns	6
Output Buffer Turn-off to $\overline{OE}$	t_{OFF2}	0	15	0	15	ns	6
CAS to D_{in} Delay Time	t_{CDD}	20	—	20	—	ns	
RAS Hold Time Referenced to $\overline{OE}$	t_{ROH}	10	—	10	—	ns	

Write Cycle

Parameter	Symbol	HM511664-8		HM511664-10		Unit	Note
		Min	Max	Min	Max		
Write Command Setup Time	t_{WCS}	0	—	0	—	ns	10
Write Command Hold Time	t_{WCH}	15	—	15	—	ns	
Write Command Pulse Width	t_{WP}	15	—	15	—	ns	
Write Command to RAS Lead Time	t_{RWL}	20	—	20	—	ns	
Write Command to CAS Lead Time	t_{CWL}	20	—	20	—	ns	
Data-in Setup Time	t_{DS}	0	—	0	—	ns	11
Data-in Hold Time	t_{DH}	15	—	15	—	ns	11



Read-Modify-Write Cycle

Parameter	Symbol	HM511664-8		HM511664-10		Unit	Note
		Min	Max	Min	Max		
Read-Modify-Write Cycle Time	t _{RWC}	185	—	220	—	ns	
RAS to WE Delay Time	t _{RWD}	105	—	125	—	ns	10
CAS to WE Delay Time	t _{CWD}	55	—	65	—	ns	10
Column Address to WE Delay Time	t _{AWD}	70	—	80	—	ns	10, 13
OE Hold Time from WE	t _{OEH}	15	—	15	—	ns	

Refresh Cycle

Parameter	Symbol	HM511664-8		HM511664-10		Unit	Note
		Min	Max	Min	Max		
CAS Setup Time (CAS Before RAS Refresh Cycle)	t _{CSR}	10	—	10	—	ns	
CAS Hold Time (CAS Before RAS Refresh Cycle)	t _{CHR}	10	—	10	—	ns	
RAS Precharge to CAS Hold Time	t _{RPC}	10	—	10	—	ns	
CAS Precharge Time in Normal Mode	t _{CPN}	10	—	10	—	ns	

Fast Page Mode Cycle

Parameter	Symbol	HM511664-8		HM511664-10		Unit	Note
		Min	Max	Min	Max		
Fast Page Mode Cycle Time	t _{PC}	55	—	65	—	ns	
Fast Page Mode CAS Precharge Time	t _{CP}	10	—	10	—	ns	
Fast Page Mode RAS Pulse Width	t _{RASC}	80	100000	100	100000	ns	12
Access Time from CAS Precharge	t _{ACP}	—	45	—	55	ns	3, 13
RAS Hold Time from CAS Precharge	t _{RHCP}	45	—	55	—	ns	
Fast Page Mode Read-Modify-Write Cycle CAS Precharge to WE Delay Time	t _{CPW}	70	—	80	—	ns	
Fast Page Mode Read-Modify-Write Cycle Time	t _{PCM}	100	—	110	—	ns	

Counter Test Cycle

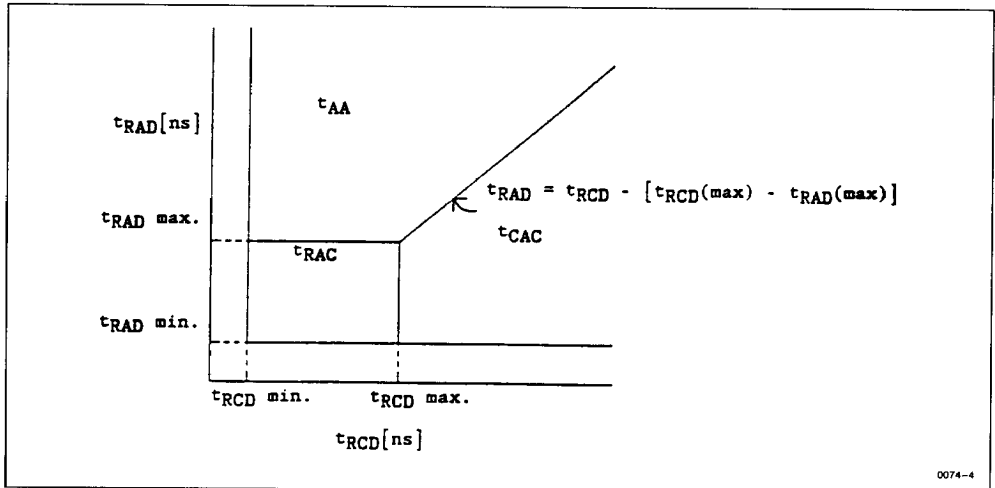
Parameter	Symbol	HM511664-8		HM511664-10		Unit	Note
		Min	Max	Min	Max		
CAS Precharge Time in Counter Test Cycle	t _{CPT}	40	—	40	—	ns	

Byte Write Mode

Parameter	Symbol	HM511664-8		HM511664-10		Unit	Note
		Min	Max	Min	Max		
Masked Write Setup Time	t _{MCS}	0	—	0	—	ns	
Masked Write Hold Time Referenced to RAS	t _{MRH}	0	—	0	—	ns	
Masked Write Hold Time Referenced to CAS	t _{MCH}	0	—	0	—	ns	



- Notes:
1. AC measurements assume $t_T = 5$ ns.
 2. Assumes that $t_{RCD} \leq t_{RCD}(\max)$ and $t_{RAD} \leq t_{RAD}(\max)$. If t_{RCD} or t_{RAD} is greater than the maximum recommended value shown in this table, t_{RAC} exceeds the value shown.
 3. Measured with a load circuit equivalent to 1 TTL load and 50 pF.
 4. Assumes that $t_{RCD} \geq t_{RCD}(\max)$ and $(t_{RCD} - t_{RAD}) \geq [t_{RCD}(\max) - t_{RAD}(\max)]$.
 5. Assumes that $t_{RAD} \geq t_{RAD}(\max)$ and $(t_{RCD} - t_{RAD}) \leq [t_{RCD}(\max) - t_{RAD}(\max)]$. t_{RAC} , t_{CAC} , and t_{AA} are determined as follows.



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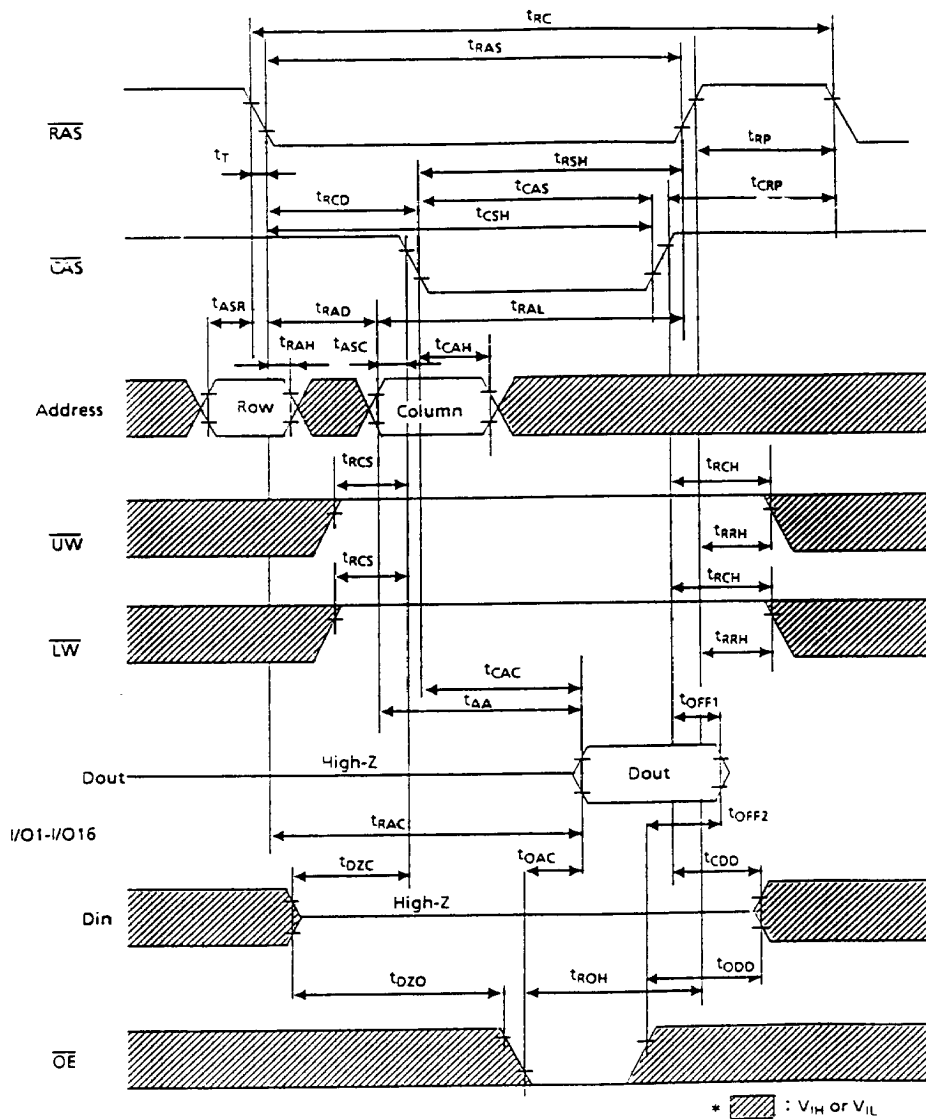
6. $t_{OFF}(\max)$ defines the time at which the output achieves the open circuit condition and is not referenced to output voltage levels.
7. $V_{IH}(\min)$ and $V_{IL}(\max)$ are reference levels for measuring timing of input signals. Also, transition times are measured between V_{IH} and V_{IL} .
8. Operation with the $t_{RCD}(\max)$ limit insures that $t_{RAC}(\max)$ can be met, $t_{RCD}(\max)$ is specified as a reference point only, if t_{RCD} is greater than the specified $t_{RCD}(\max)$ limit, then access time is controlled exclusively by t_{CAC} .
9. Operation with the $t_{RAD}(\max)$ limit insures that $t_{RAC}(\max)$ can be met, $t_{RAD}(\max)$ is specified as a reference point only, if t_{RAD} is greater than the specified $t_{RAD}(\max)$ limit, then access time is controlled exclusively by t_{AA} .
10. t_{WCS} , t_{RWD} , t_{CWD} and t_{AWD} are not restrictive operating parameters. They are included in the data sheet as electrical characteristics only: if $t_{WCS} \geq t_{WCS}(\min)$, the cycle is an early write cycle and the data out pin will remain open circuit (high impedance) throughout the entire cycle; if $t_{RWD} \geq t_{RWD}(\min)$, $t_{CWD} \geq t_{CWD}(\min)$, $t_{AWD} \geq t_{AWD}(\min)$ and $t_{CPW} \geq t_{CPW}(\min)$, the cycle is a read-modify-write and the data output will contain data read from the selected cell; if neither of the above sets of conditions is satisfied, the condition of the data out (at access time) is indeterminate.
11. These parameters are referenced to $\overline{CAS}$ leading edge in an early write cycle and to $\overline{WE}$ leading edge in a delayed write or a read-modify-write cycle.
12. t_{RASC} defines $\overline{RAS}$ pulse width in fast page mode cycles.
13. Access time is determined by the longer of t_{AA} or t_{CAC} or t_{ACP} .
14. An initial pause of 100 μs is required after power up followed by a minimum of eight initialization cycles ($\overline{RAS}$ only refresh cycle or $\overline{CAS}$ before $\overline{RAS}$ refresh cycle). If the internal refresh counter is used, a minimum of eight $\overline{CAS}$ before $\overline{RAS}$ refresh cycles is required.
15. In delayed write or read-modify-write cycles, OE must disable output buffer prior to applying data to the device.
16. When both $\overline{LW}$ and $\overline{UW}$ go low at the same time, all 16-bits data are written into the device. $\overline{LW}$ and $\overline{UW}$ cannot be staggered within the same write cycle.



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■ TIMING WAVEFORMS

• Read Cycle

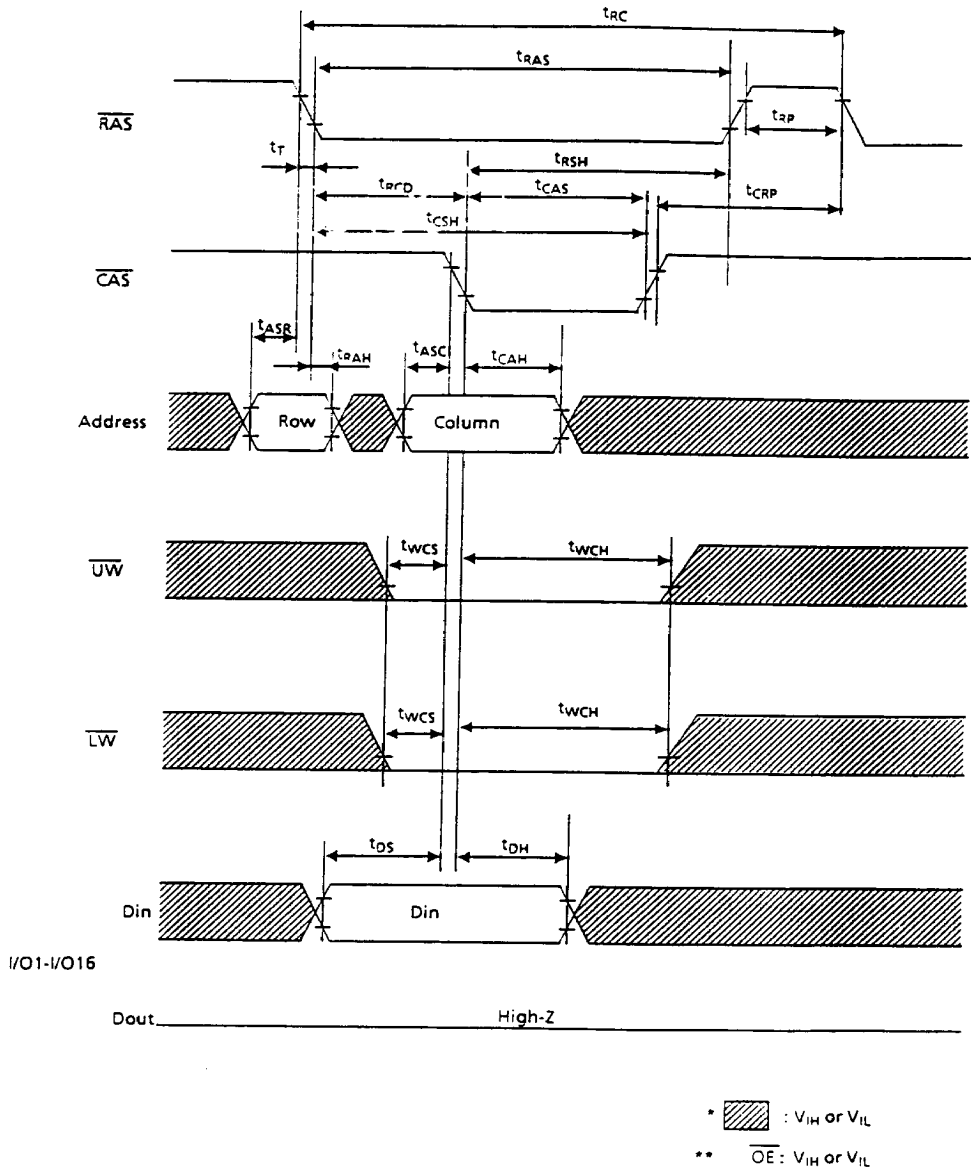


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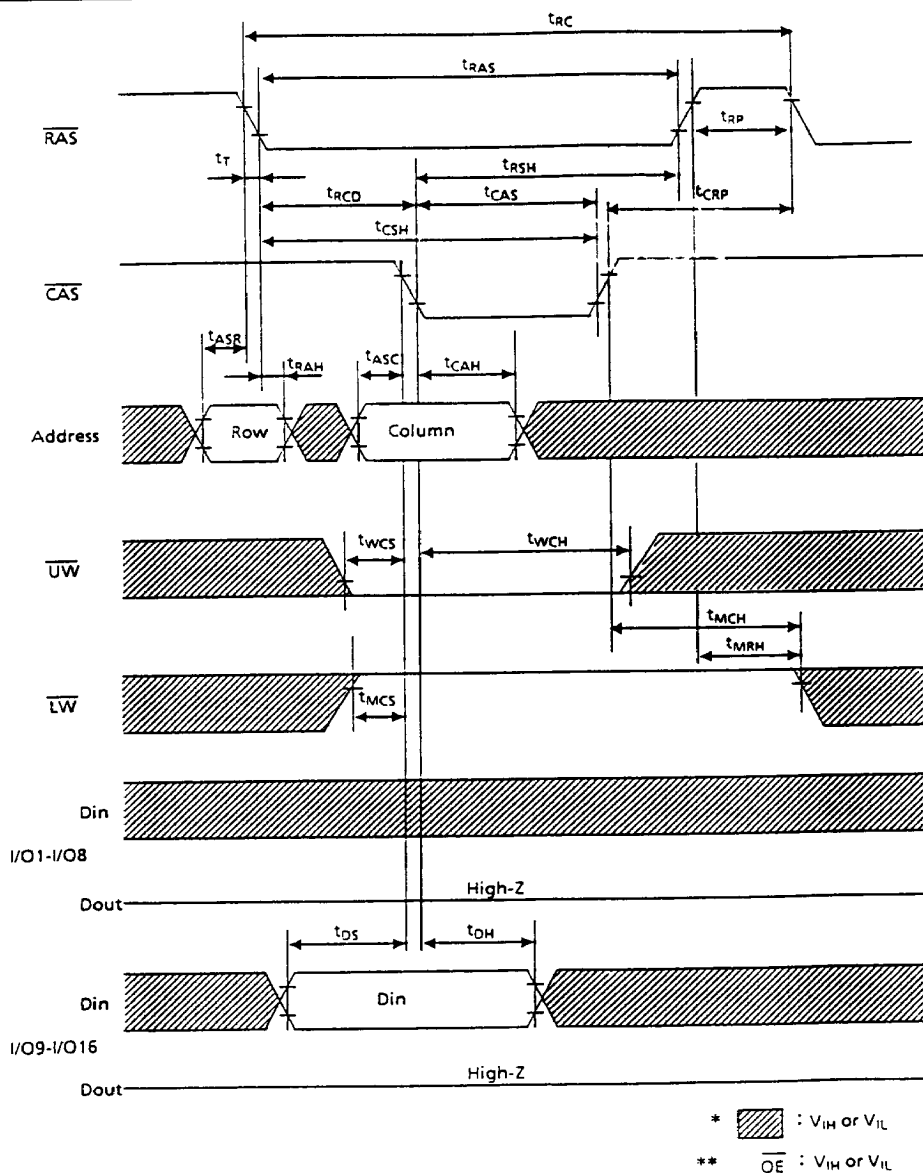
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0074-6



• Upper Byte Early Write Cycle



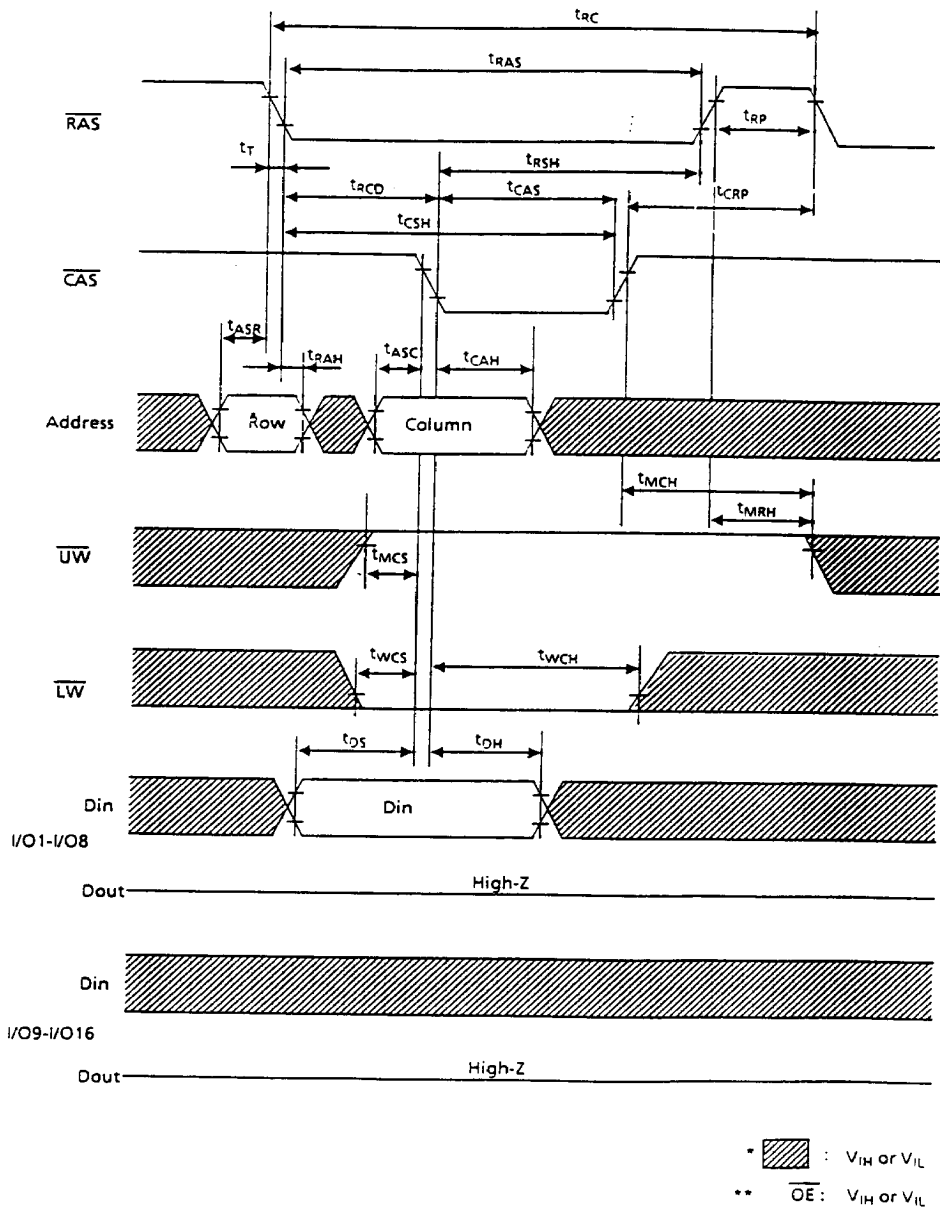
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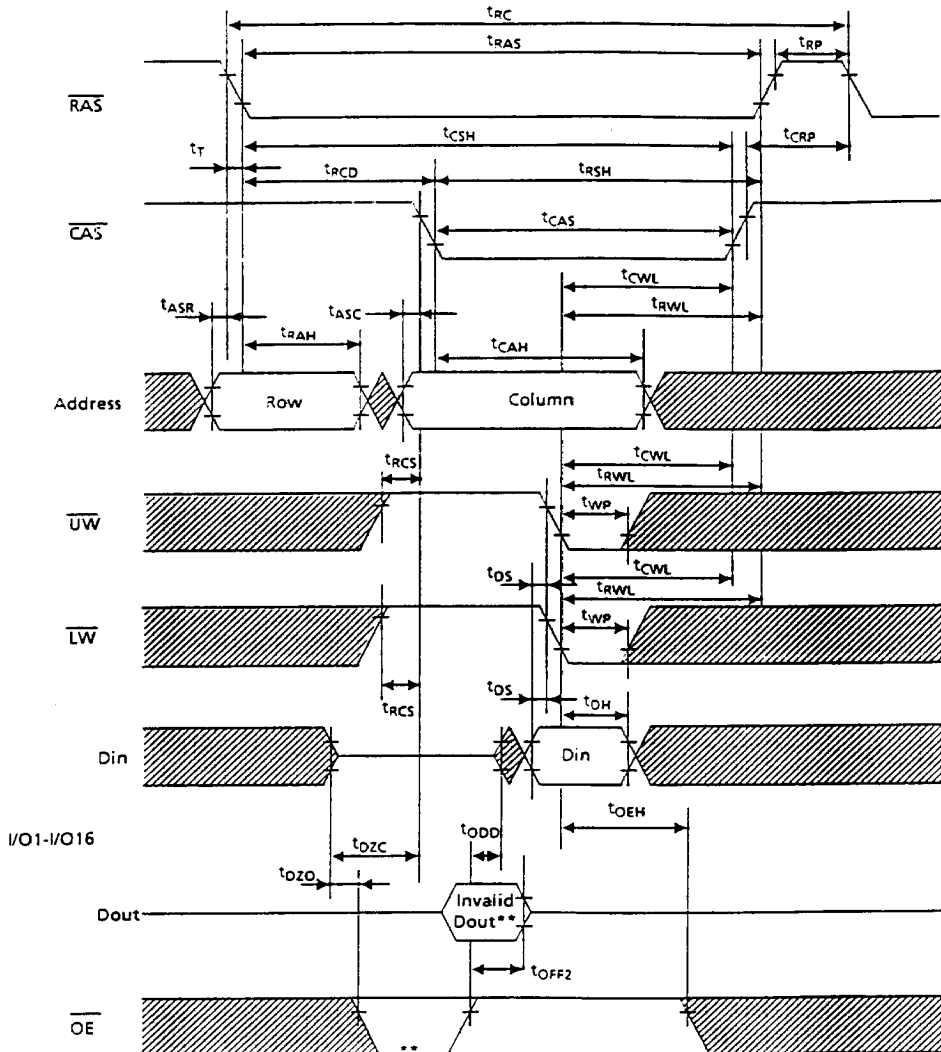
• Lower Byte Early Write Cycle



0074-B



• Delayed Write Cycle



* : V_{IH} or V_{IL}

** Invalid Dout comes out, when $\overline{OE}$ is low level.

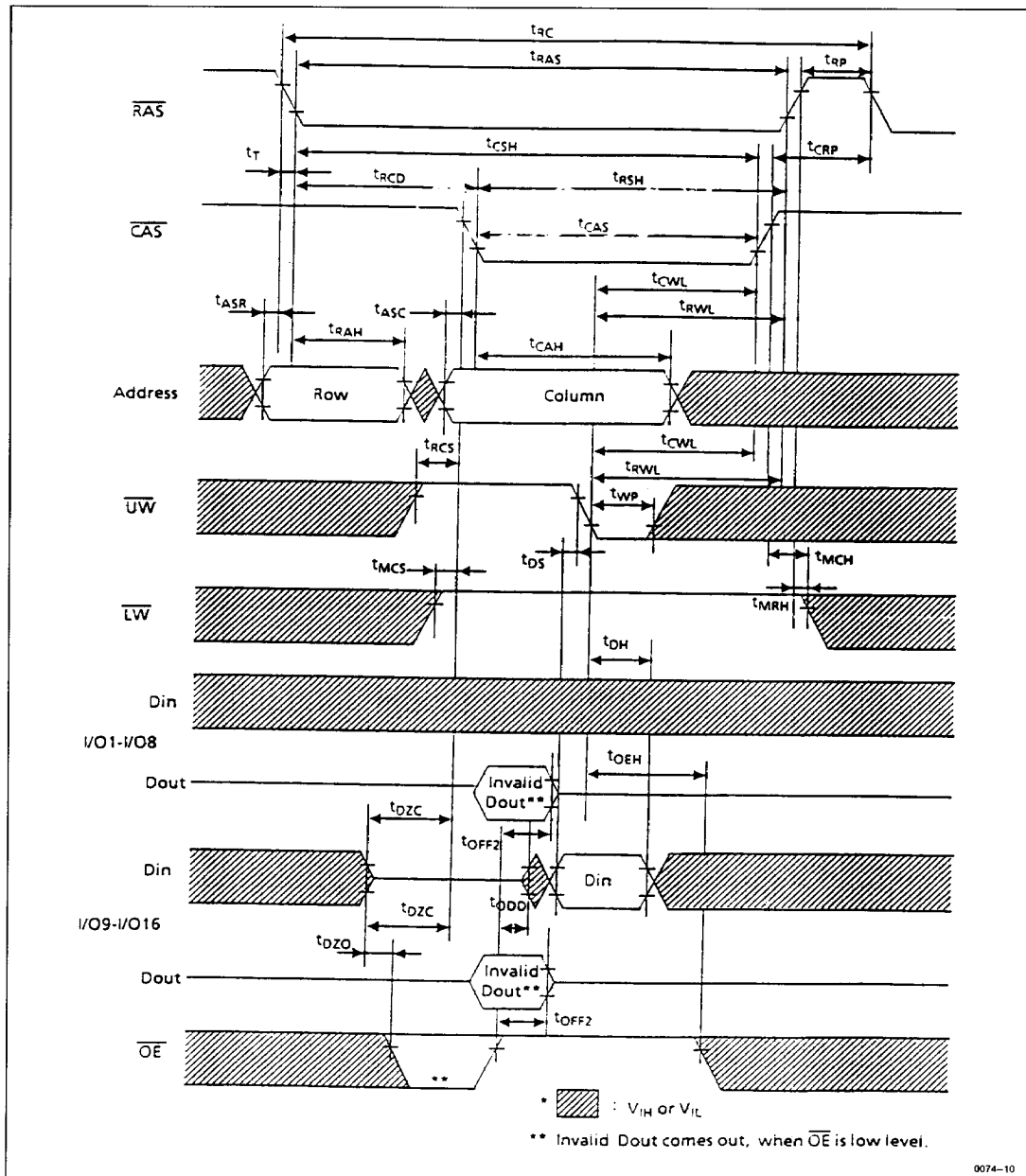
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• Upper Byte Delayed Write Cycle



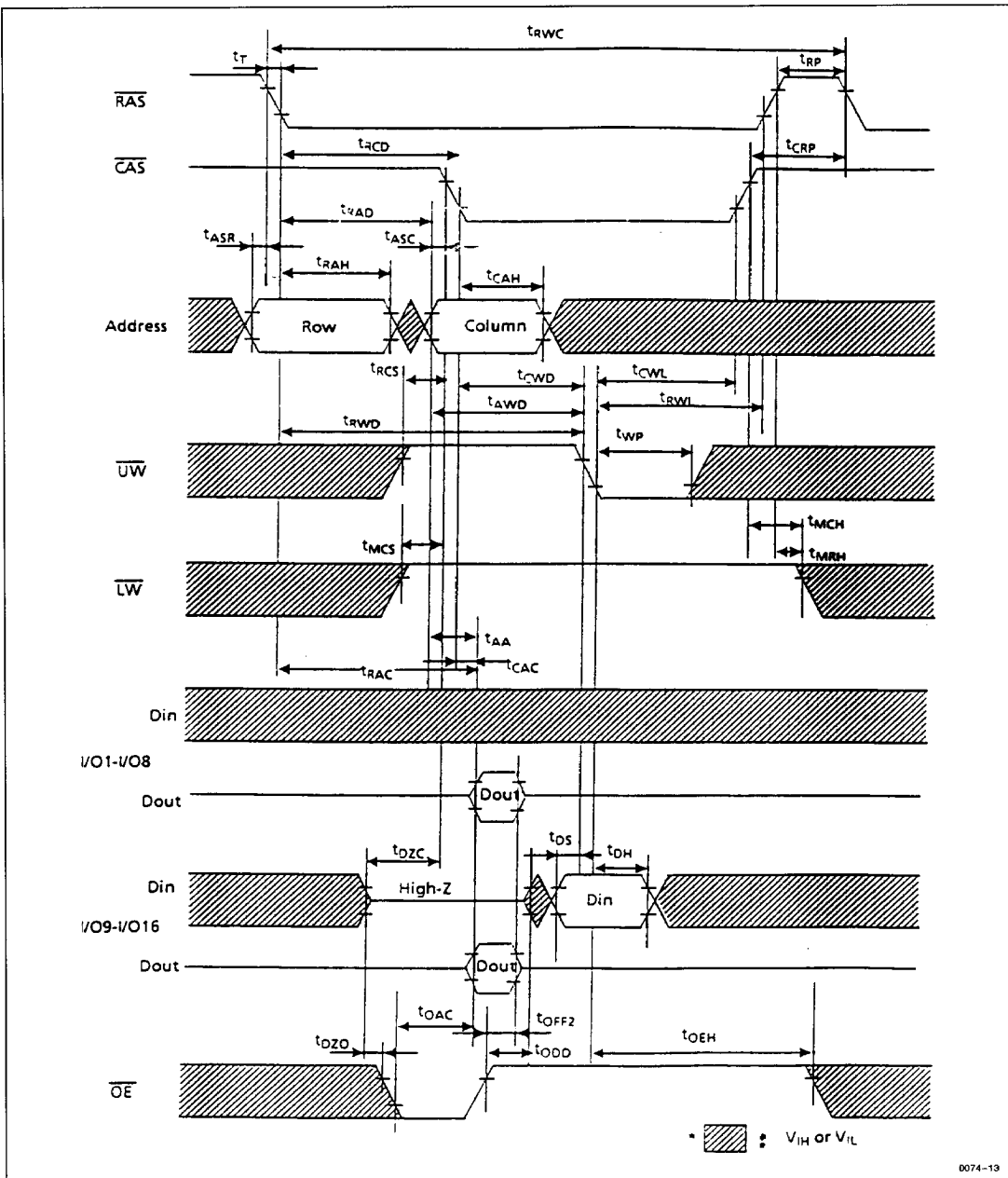
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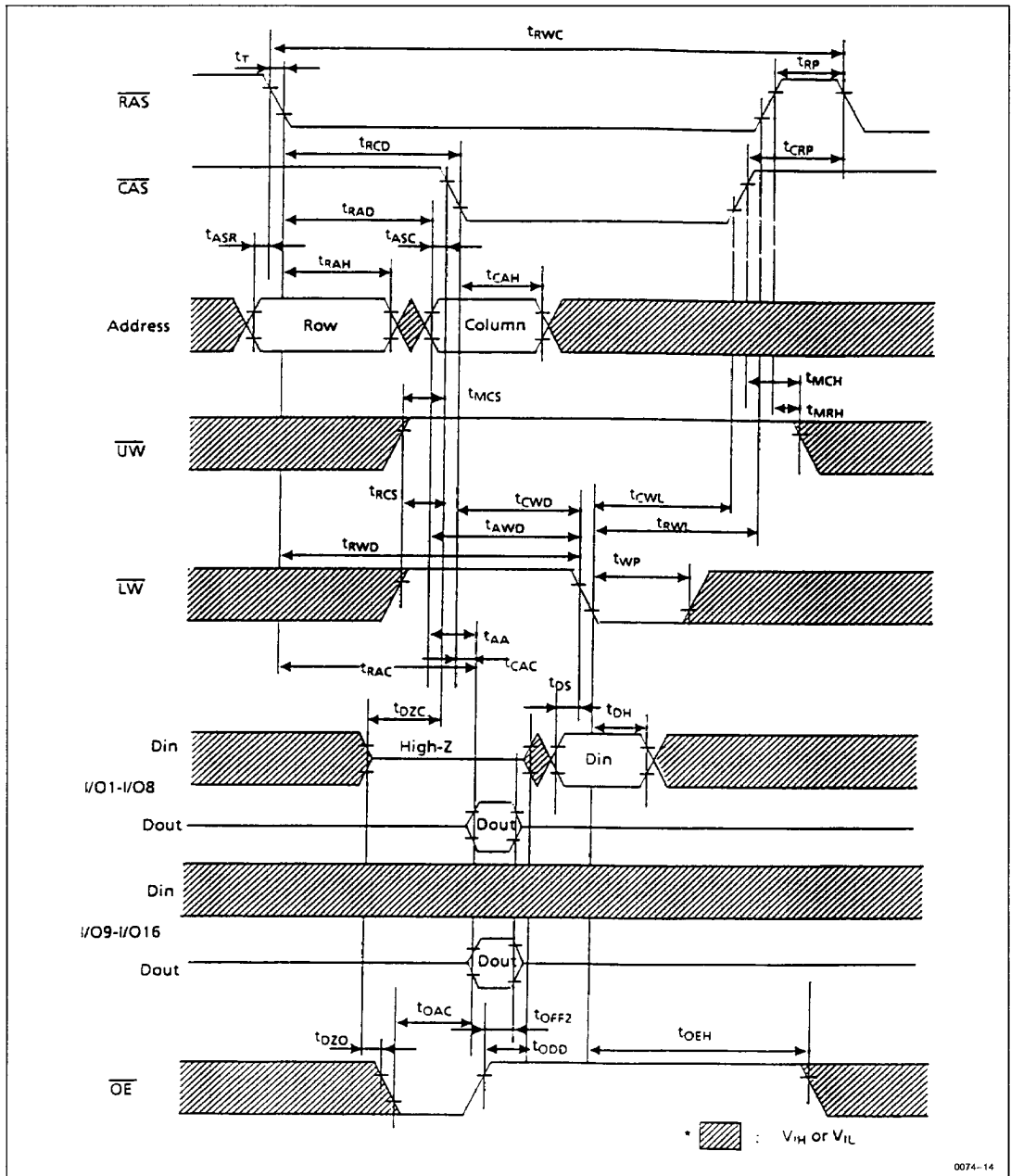
• Read Modify Upper Byte Write Cycle



0074-13

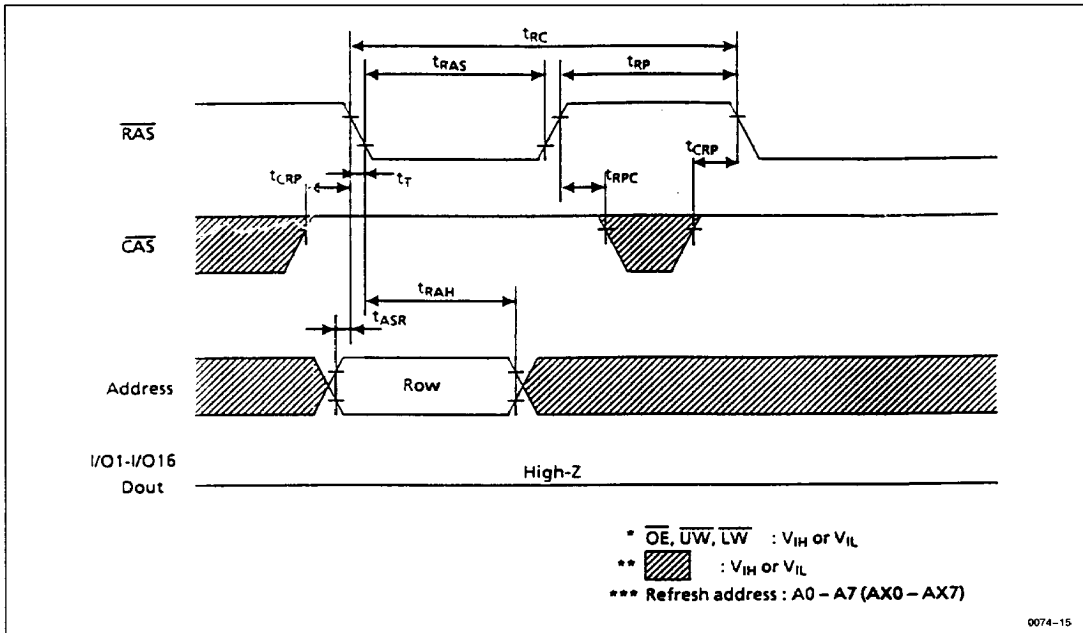
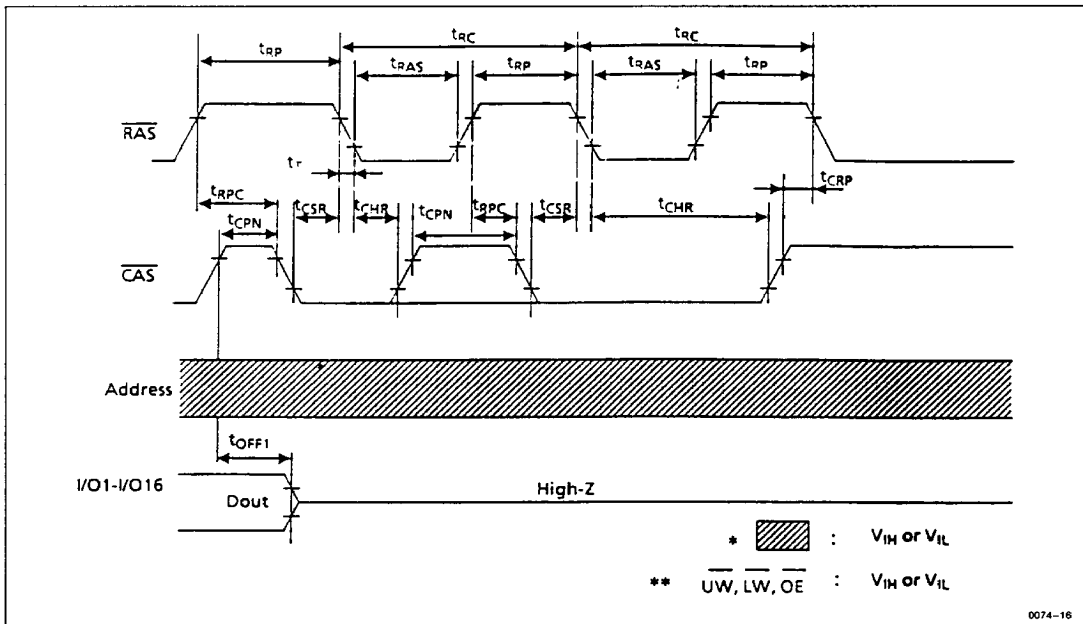


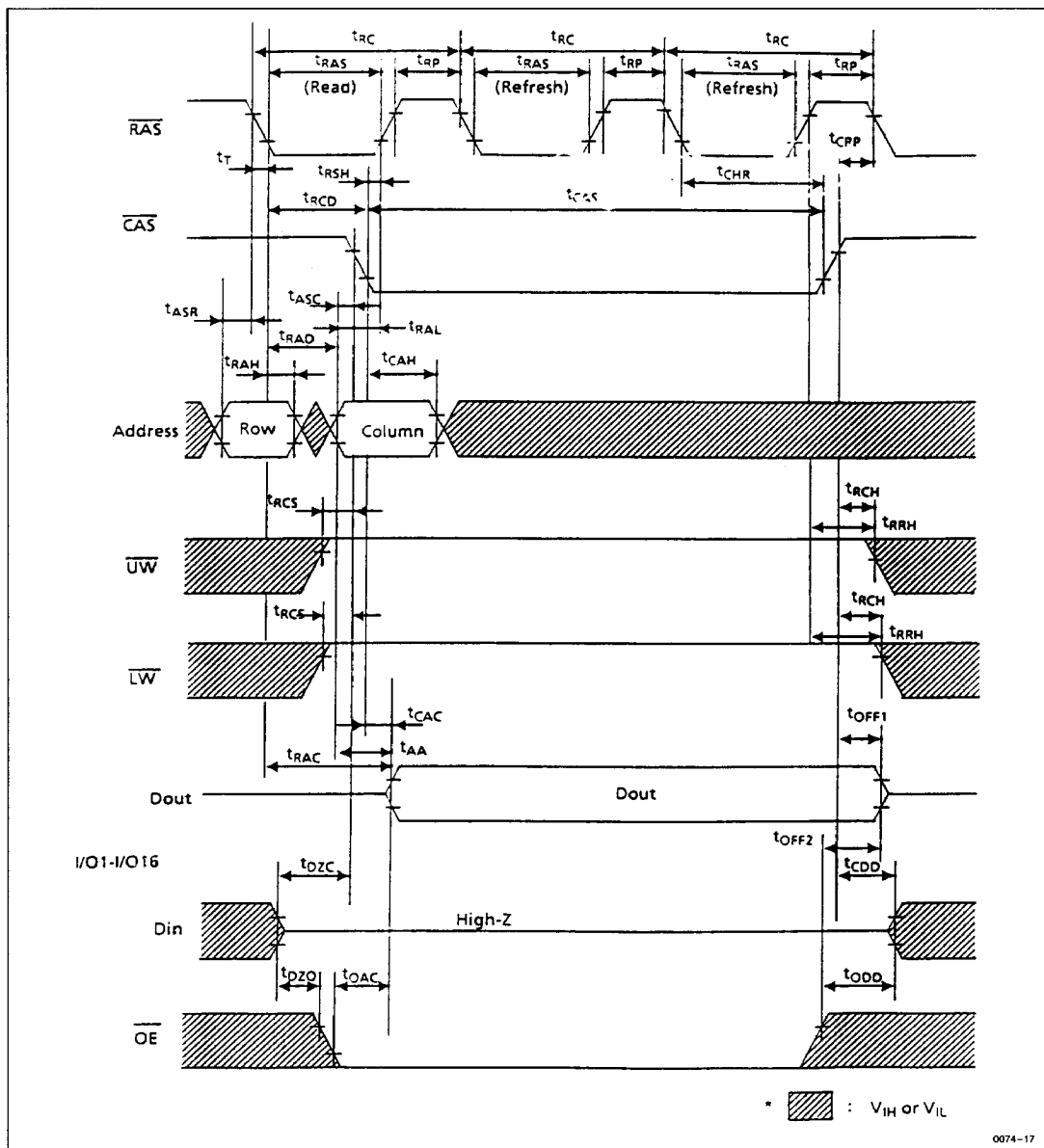
• Read Modify Lower Byte Write Cycle



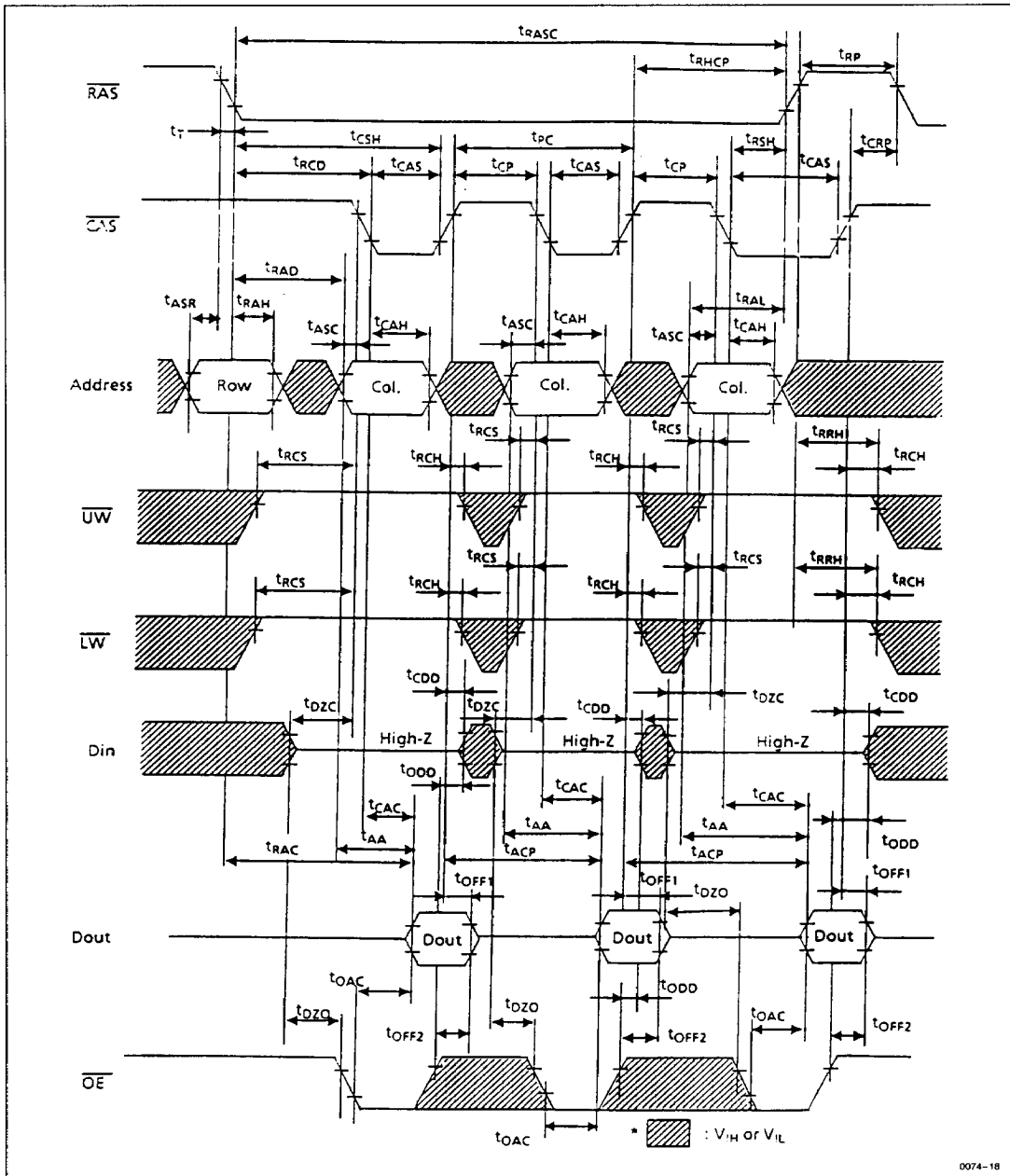
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• **RAS Only Refresh Cycle**• **CAS Before RAS Refresh Cycle**



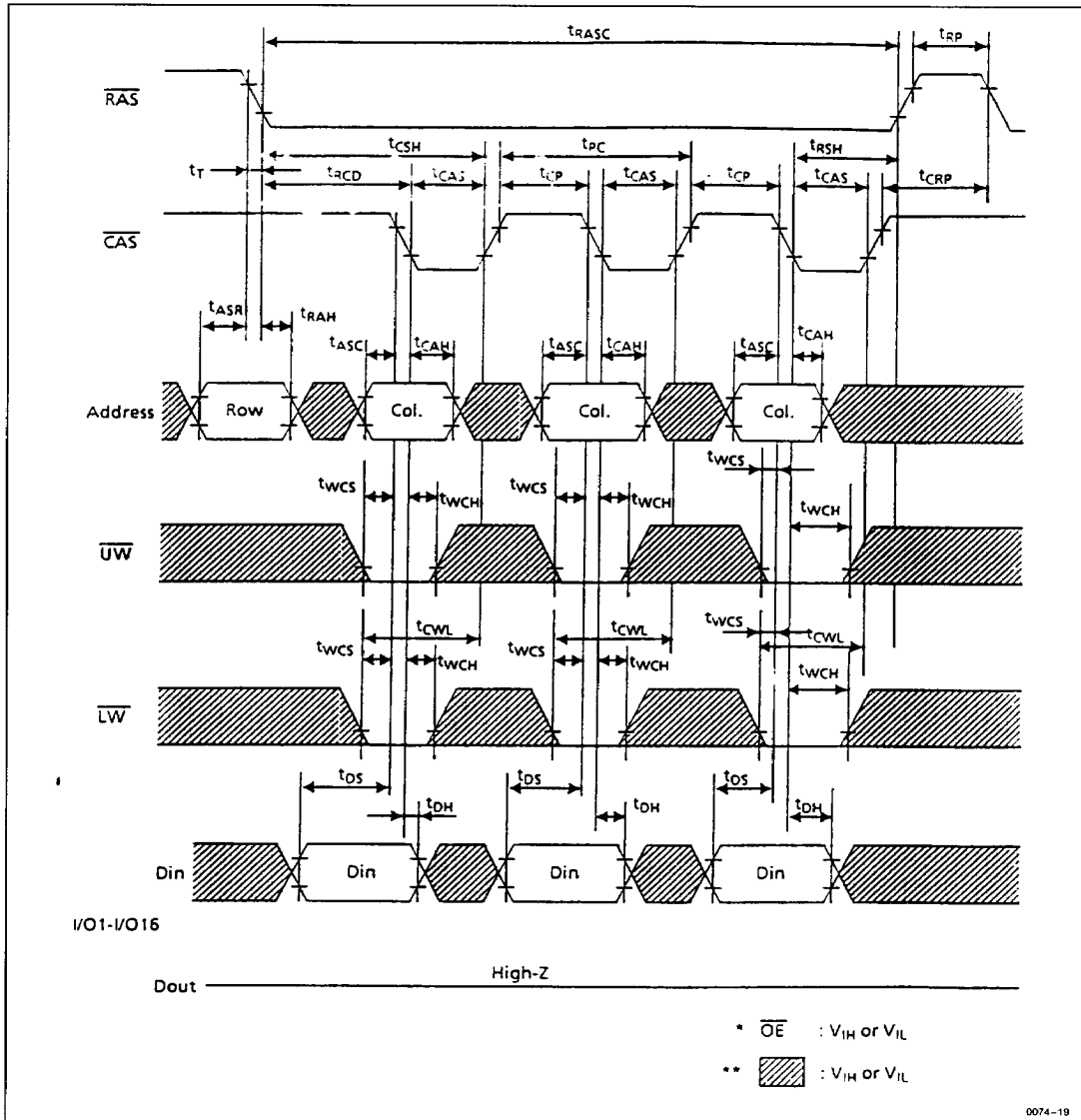
• Fast Page Mode Read Cycle



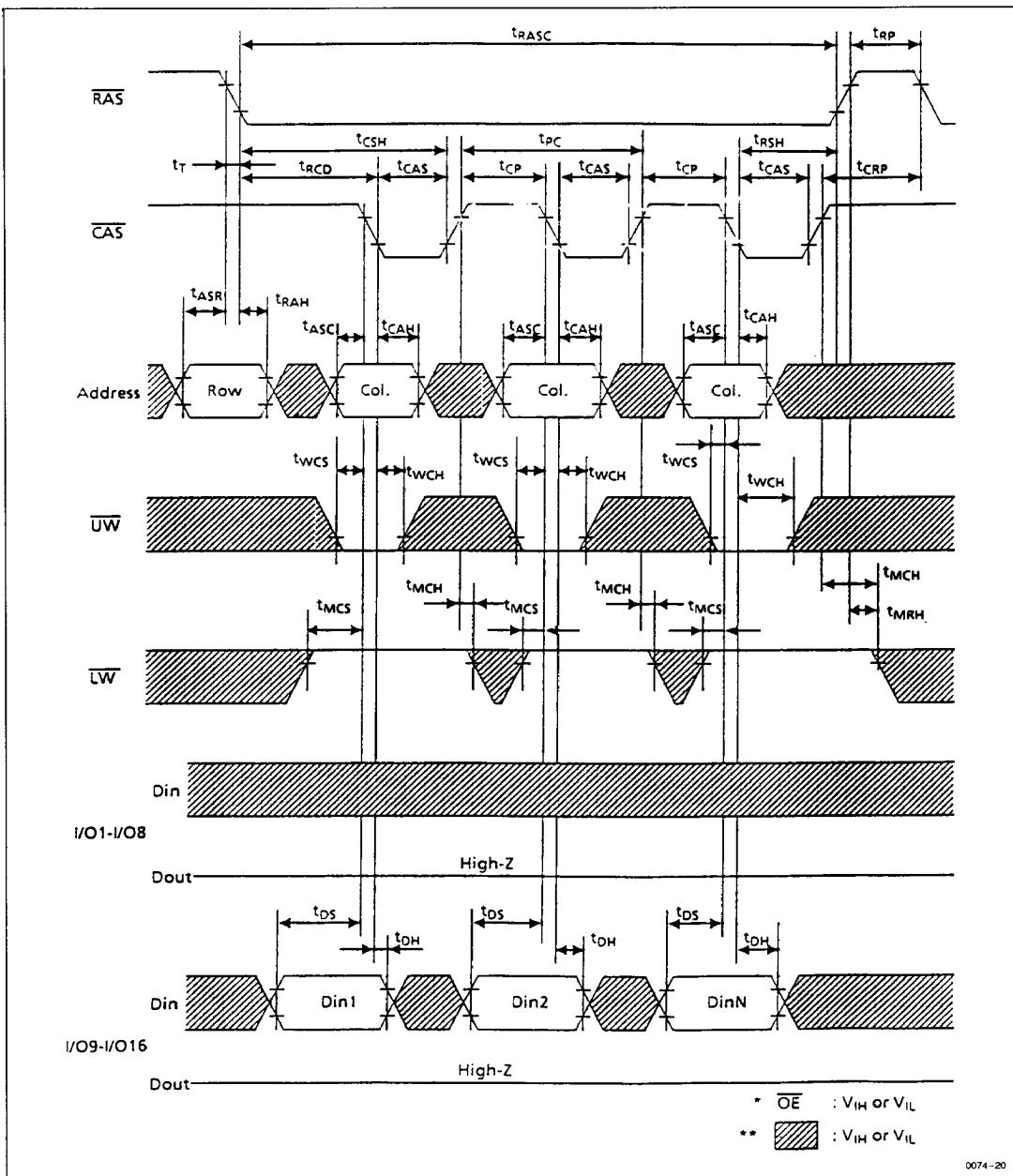
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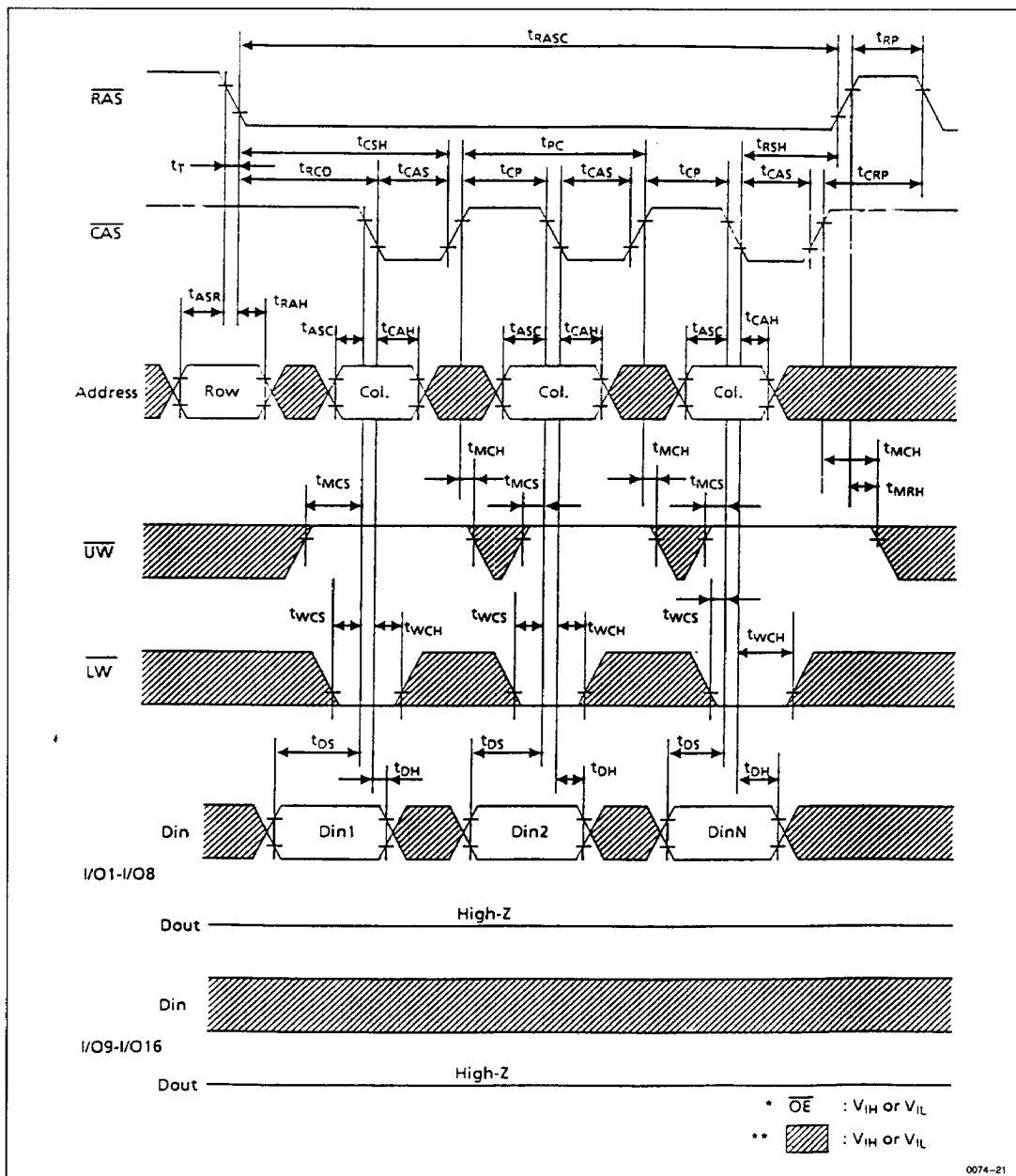
• Fast Page Mode Early Write Cycle



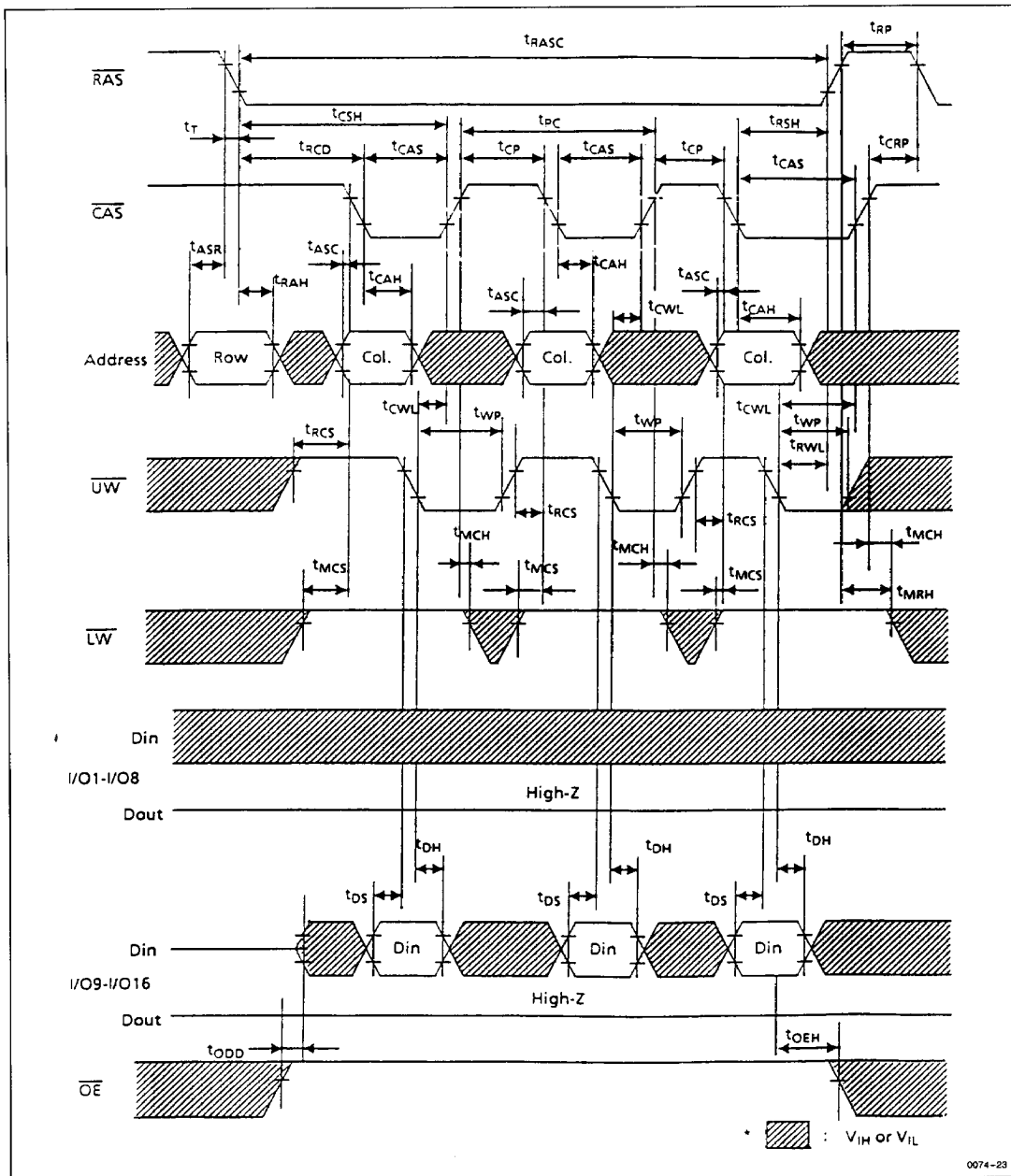
• Fast Page Mode Upper Byte Early Write Cycle



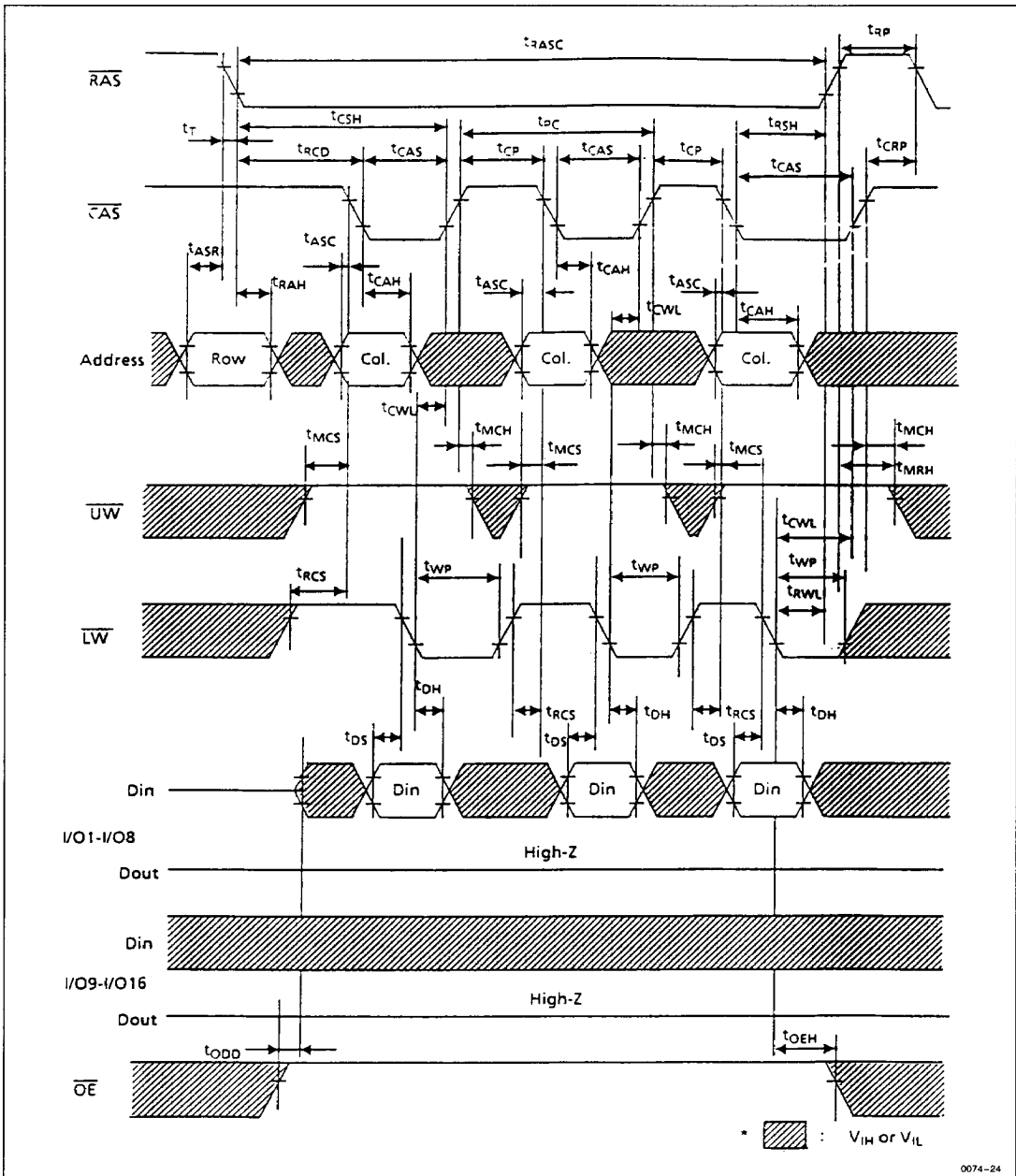
• Fast Page Mode Lower Byte Early Write Cycle







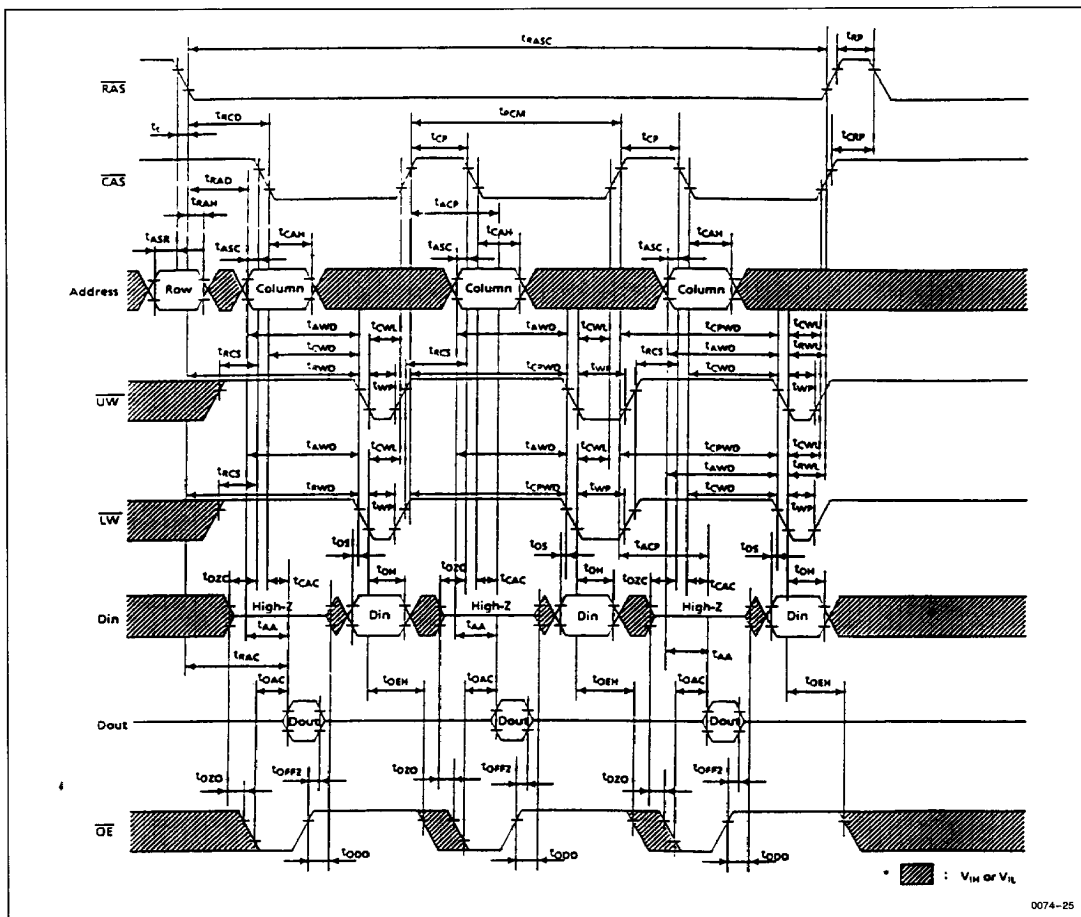
• Fast Page Mode Lower Byte Delayed Write Cycle

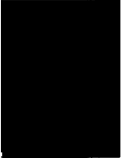


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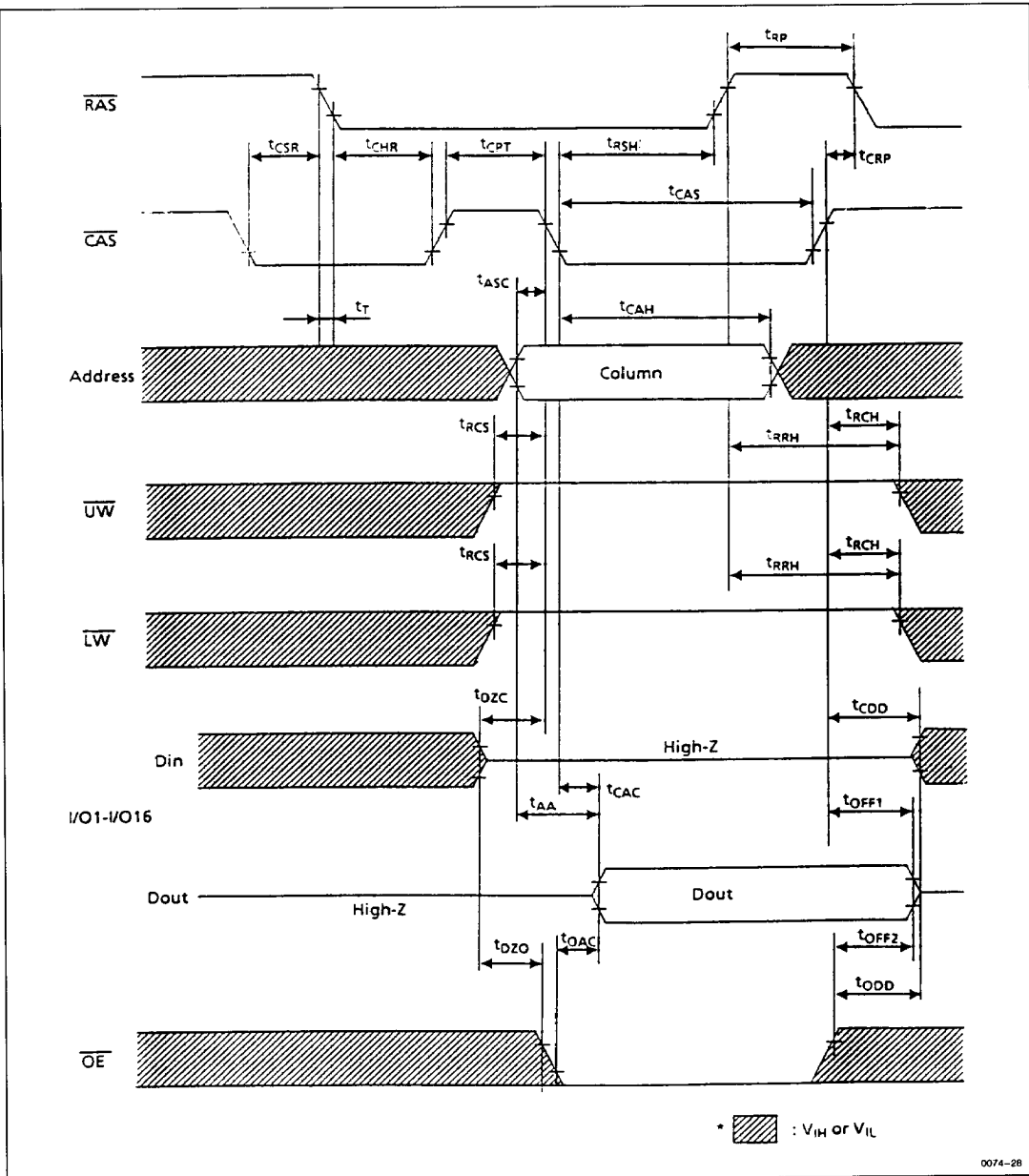


• Fast Page Mode Read-Modify-Write Cycle

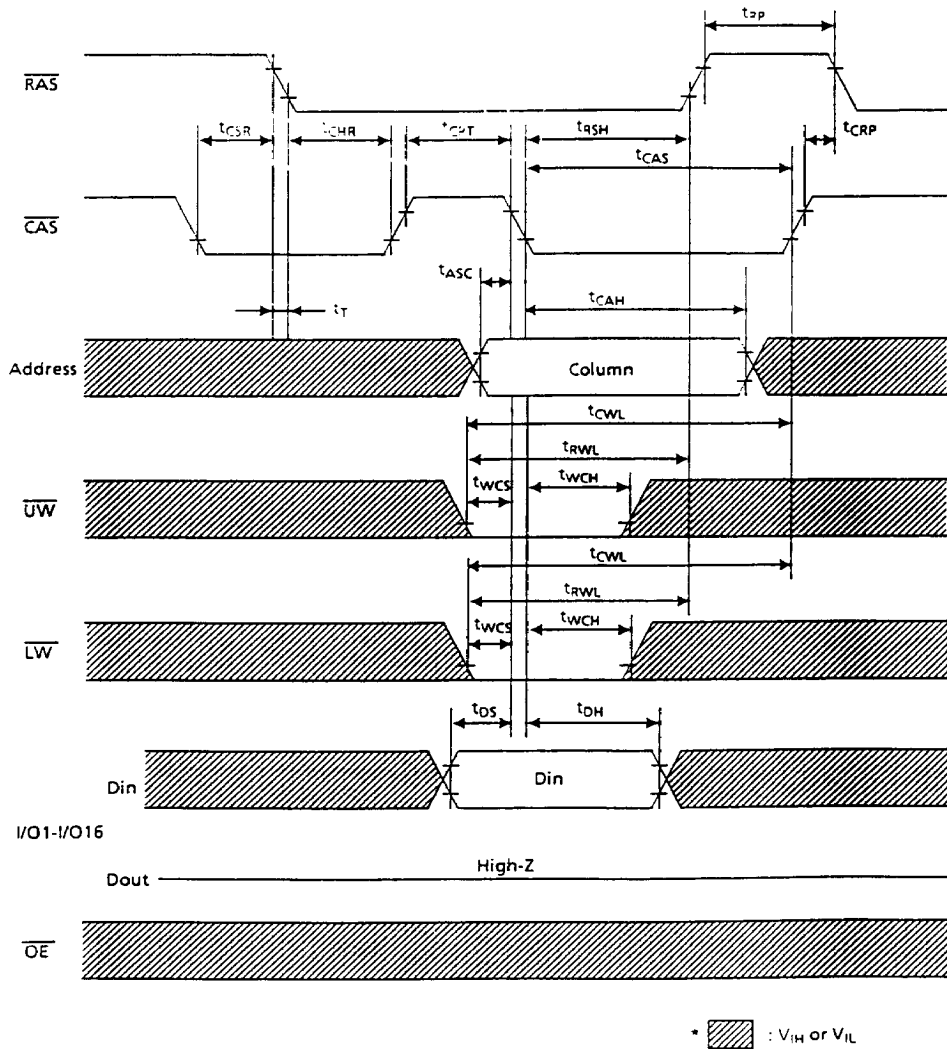






• **CAS Before RAS Refresh Counter Check Cycle (Read)**

• CAS Before RAS Refresh Counter Check Cycle (Write)



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